



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-11-06
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST715MR	HVWV*UL56J51	A	ZS1A	2015-11-06
Amount		UoM	Unit type	ST ECOPACK Grade
16.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.8 - 1.5 - 0.9	5	gull wing	
Comment	Package: SOT 23 5L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HWVW*UL56J51					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.516	mg	supplier	die	Silicon (Si)	7440-21-3		0.488	mg	945736	30500
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	11628	375
				supplier	metallization	Tungsten (W)	7440-33-7		0.005	mg	9690	313
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	1938	63
				supplier	Passivation	Silicon Oxide	7631-86-9		0.010	mg	19380	625
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.006	mg	11628	375
Leadframe	Copper & its alloys	7.057	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.799	mg	963441	424938
				supplier	alloy	Iron (Fe)	7439-89-6		0.158	mg	22389	9875
				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	283	125
				supplier	alloy	Zinc (Zn)	7440-66-6		0.009	mg	1275	563
				supplier	metallization	Nickel (Ni)	7440-02-0		0.081	mg	11478	5063
				supplier	metallization	Palladium (Pd)	7440-05-3		0.007	mg	992	438
Die attach	Other Organic Materials	0.066	mg	supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	142	63
				supplier	glue	Silver (Ag)	7440-22-4		0.046	mg	696970	2875
				supplier	glue	methylene diacrylate	42594-17-2		0.016	mg	242424	1000
				supplier	glue	Dicyclopentenylxyethyl methacrylate	68586-19-6		0.002	mg	30303	125
				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.002	mg	30303	125
				supplier	wire	Gold (Au)	7440-57-5		0.147	mg	1000000	9188
Encapsulation	Other Organic Materials	8.214	mg	supplier	molding compound	Silica, vitreous	60676-86-0		7.375	mg	897857	460938
				supplier	molding compound	phenolic resin	29690-82-2		0.303	mg	36888	18938
				supplier	molding compound	epoxy resin	25068-38-6		0.346	mg	42123	21625
				supplier	molding compound	Biphenyl epoxy resin	85954-11-6		0.173	mg	21062	10813
				supplier	molding compound	carbon black	1333-86-4		0.017	mg	2070	1063